



SPECIFICATION

(Reference sheet)

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N :
 Description :
- CL10C3R5CB8NNNC CAP, 3.5pF, 50V, ± 0.25pF, C0G, 0603

A. Samsung Part Number

| | | | <u>CL</u> | <u>10</u> | <u>C</u> | <u>3R5</u> | <u>C</u> | <u>B</u> | <u>8</u> | N | <u>N</u> | N | <u>C</u> | |
|---|---------------|------------|-----------|-----------|----------|------------|----------|----------|----------|------|----------|----|------------------|------------|
| | | | 1 | 2 | 3 | 4 | 5 | 6 | 1 | 8 | 9 | 10 | 1 | |
| 1 | Series | Samsung | Multi-lay | er Ce | rami | с Сара | acitor | | | | | | | |
| 2 | Size | 0603 | (inch co | ode) | | L: | 1.60 | ± 0.10 | mm | | | W: | 0.80 ± 0.10 mm | |
| 3 | Dielectric | C0G | i | | | | 8 | Inner | elect | rode | | | Ni | |
| 4 | Capacitance | 3.5 | рF | | | | | Term | inatic | on | | | Cu | |
| 5 | Capacitance | ± 0.2 | 25pF | | | | | Platir | ng | | | | Sn 100% | (Pb Free) |
| | tolerance | | | | | | 9 | Prod | uct | | | | Normal | |
| 6 | Rated Voltage | 50 | V | | | | 10 | Spec | ial | | | | Reserved for fut | ture use |
| 1 | Thickness | 0.80 ± 0.1 | 0 mm | | | | 1 | Pack | aging | | | | Cardboard Type | e, 7" reel |

B. Structure and dimension



| Samsung P/N | Dimension(mm) | | | | | | | | |
|-----------------|---------------|-------------|-------------|-------------|--|--|--|--|--|
| (Lead Free) | L | W | Т | BW | | | | | |
| CL10C3R5CB8NNNC | 1.60 ± 0.10 | 0.80 ± 0.10 | 0.80 ± 0.10 | 0.30 ± 0.20 | | | | | |

C. Samsung Reliability Test and Judgement condition

| Q Insulation Resistance Appearance Withstanding Voltage Temperature Characteristics Adhesive Strength of Termination Bending Strength | Within specified tolerance 470 min 10,000Mohm or 500Mohm×µF Whichever is smaller No abnormal exterior appearance No dielectric breakdown or mechanical breakdown COG (From -55 ℃ to 125 ℃, Capacitance change sh No peeling shall be occur on the terminal electrode Capacitance change : within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface is to be soldered newly | 1Mi±±10% / 0.5~5Vrms Rated Voltage 60~120 sec. Microscop (X10) 300% of the rated voltage hould be within ±30PPM/°C) 500g×F, for 10±1 sec. Bending to the limit (1mm) with 1.0mm/sec. SnAg3.0Cu0.5 solder 245±5 °C, 3±0.3sec. |
|---|--|--|
| Insulation Resistance Appearance Withstanding Voltage Temperature Characteristics Adhesive Strength of Termination Bending Strength | 10,000Mohm or 500Mohm×µF Whichever is smaller No abnormal exterior appearance No dielectric breakdown or mechanical breakdown C0G (From -55 ℃ to 125 ℃, Capacitance change sh No peeling shall be occur on the terminal electrode Capacitance change : within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface | Microscop (X10) 300% of the rated voltage hould be within ±30PPM/°C) 500g×F, for 10±1 sec. Bending to the limit (1mm) with 1.0mm/sec. SnAg3.0Cu0.5 solder |
| ResistanceAppearanceWithstandingVoltageTemperatureCharacteristicsAdhesive Strengthof TerminationBending Strength | Whichever is smaller No abnormal exterior appearance No dielectric breakdown or mechanical breakdown COG (From -55 °C to 125 °C, Capacitance change sh No peeling shall be occur on the terminal electrode Capacitance change : within ±5% or ±0.5 pF whichever is larger More than 75% of terminal surface | Microscop (X10) 300% of the rated voltage hould be within ±30PPM/°C) 500g×F, for 10±1 sec. Bending to the limit (1mm) with 1.0mm/sec. SnAg3.0Cu0.5 solder |
| AppearanceWithstandingVoltageTemperatureCharacteristicsAdhesive Strengthof TerminationBending Strength | No abnormal exterior appearance No dielectric breakdown or mechanical breakdown C0G (From -55 °C to 125 °C, Capacitance change sh No peeling shall be occur on the terminal electrode Capacitance change : within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface | 300% of the rated voltage hould be within ±30PPM/℃) 500g×F, for 10±1 sec. Bending to the limit (1mm) with 1.0mm/sec. SnAg3.0Cu0.5 solder |
| Withstanding I Voltage I Temperature I Characteristics I Adhesive Strength I of Termination I Bending Strength I | No dielectric breakdown or mechanical breakdown C0G (From -55 °C to 125 °C, Capacitance change sł No peeling shall be occur on the terminal electrode Capacitance change : within ±5% or ±0.5 pF whichever is larger More than 75% of terminal surface | 300% of the rated voltage hould be within ±30PPM/℃) 500g×F, for 10±1 sec. Bending to the limit (1mm) with 1.0mm/sec. SnAg3.0Cu0.5 solder |
| Voltage Temperature Characteristics Adhesive Strength of Termination Bending Strength | mechanical breakdown C0G (From -55 °C to 125 °C, Capacitance change sh No peeling shall be occur on the terminal electrode Capacitance change : within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface | hould be within ±30PPM/℃) 500g×F, for 10±1 sec. Bending to the limit (1mm) with 1.0mm/sec. SnAg3.0Cu0.5 solder |
| Temperature Characteristics Adhesive Strength of Termination Bending Strength | C0G (From -55°C to 125°C, Capacitance change sh No peeling shall be occur on the terminal electrode Capacitance change : within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface | 500g×F, for 10±1 sec. Bending to the limit (1mm) with 1.0mm/sec. SnAg3.0Cu0.5 solder |
| Characteristics Adhesive Strength of Termination Bending Strength | (From -55°C to 125°C, Capacitance change sh No peeling shall be occur on the terminal electrode Capacitance change : within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface | 500g×F, for 10±1 sec. Bending to the limit (1mm) with 1.0mm/sec. SnAg3.0Cu0.5 solder |
| Adhesive Strength of Termination Bending Strength | No peeling shall be occur on the terminal electrode Capacitance change : within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface | 500g×F, for 10±1 sec. Bending to the limit (1mm) with 1.0mm/sec. SnAg3.0Cu0.5 solder |
| of Termination Bending Strength | terminal electrode Capacitance change : within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface | Bending to the limit (1mm) with 1.0mm/sec. SnAg3.0Cu0.5 solder |
| Bending Strength | Capacitance change : within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface | with 1.0mm/sec. SnAg3.0Cu0.5 solder |
| | within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface | with 1.0mm/sec. SnAg3.0Cu0.5 solder |
| | More than 75% of terminal surface | SnAg3.0Cu0.5 solder |
| Solderability | | 5 |
| | is to be soldered newly | 245+5°C, 3+0,3sec. |
| l | | |
| | | (preheating : 80~120 ℃ for 10~30sec.) |
| Resistance to | Capacitance change : | Solder pot : 270±5℃, 10±1sec. |
| | within $\pm 2.5\%$ or ± 0.25 pF whichever is larger | |
| - | Tan δ , IR : initial spec. | |
| | Capacitance change : | Amplitude : 1.5mm |
| | within $\pm 2.5\%$ or ± 0.25 pF whichever is larger | From 10Hz to 55Hz (return : 1min.) |
| | Tan δ, IR : initial spec. | 2hours ' 3 direction (x, y, z) |
| | Capacitance change : | With rated voltage |
| | within $\pm 7.5\%$ or ± 0.75 pF whichever is larger | 40±2℃, 90~95%RH, 500+12/-0hrs |
| | Q: 111.67 min | |
| | IR : 500Mohm or 25Mohm × μ F | |
| | Whichever is smaller | |
| High Temperature | Capacitance change : | With 200% of the rated voltage |
| | within $\pm 3\%$ or ± 0.3 pF whichever is larger | Max. operating temperature |
| | Q: 235 min | 1000+48/-0hrs |
| | IR : 1,000Mohm or 50Mohm × μF | |
| | Whichever is smaller | |
| Temperature | Capacitance change : | 1 cycle condition |
| - | within $\pm 2.5\%$ or ± 0.25 pF whichever is larger | Min. operating temperature $\rightarrow 25^{\circ}$ C |
| | Tan δ , IR : initial spec. | \rightarrow Max. operating temperature \rightarrow 25 °C |
| | | |
| | | 5 cycle test |

* The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time. So, you need to approve the product specifications before placing an order. Should you have any question regarding the product specifications, please contact our sales personnel or application engineers.

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The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

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If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- Aerospace/Aviation equipment
- ② Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- *④ Military equipment*
- *5* Disaster prevention/crime prevention equipment
- *(c)* Any other applications with the same as or similar complexity or reliability to the applications set forth above.